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(54) Process of making a baked piece comprising two or more wafer layers

(57) A baked piece comprising two or more wafer layers is made from a discrete baked wafer cake folding the cake at least once when it is warm and deformable and introducing at least one edible filling material between the layers as said wafer cake is folded. A food, such as butter, to prevent an ingress of moisture is optionally applied to at least one side of the wafer cake before the latter is folded. The baked piece is optionally trimmed at an edge thereof.

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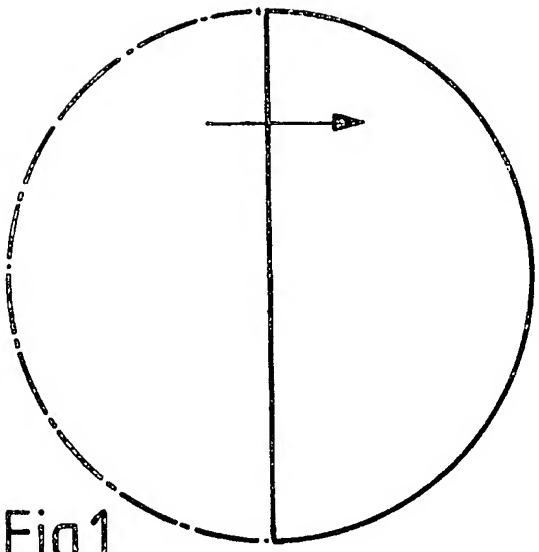

Fig.1

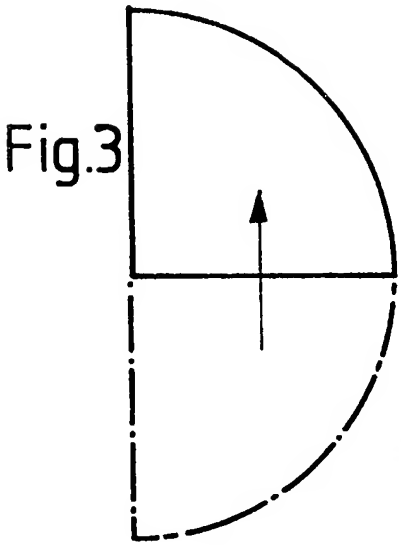

Fig.3

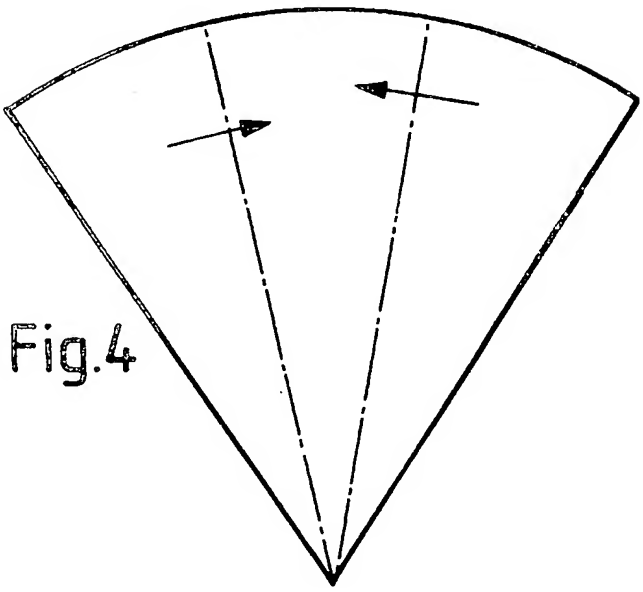

Fig.4

Fig.5

Fig.6

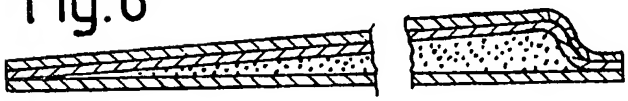

Fig.2

SPECIFICATION

Process of making a baked piece comprising two or more wafer layers from a substantially flat, discrete wafer cake baked from wafer dough

BACKGROUND OF THE INVENTION

Field of the Invention

This invention relates to the making of a baked piece from a substantially flat, discrete wafer cake baked from wafer dough, wherein said wafer cake is folded at least once in a soft and deformable state to form a laminated baked piece comprising at least two wafer layers, which define at least one cavity.

Description of the Prior Art

Flat wafer cakes, which may be provided with an engraved texture, as well as wafer sheets or low hollow wafers are made in wafer-baking ovens comprising revolving baking tongs. Such wafer products belong to the wafer products which are made by machines in the foodstuffs and luxury food industry and are offered for sale in a filled or unfilled state and are generally regarded as luxury foods. Said products of the wafer industry include rolled wafer cones, sugar cones, sweet wafer cones and wafer rolls, also other wafer products, such as cast wafer cones, wafer cups, wafer plates, flat wafer discs, low hollow wafers, hollow rods, cones for ice cream, filled wafers, wafers for ice cream, small filled wafer rods, wafer slices and the like.

Such wafer products are baked products, which are made from wafer dough and have a crisp, brittle and fragile consistency. They are baked to be as dry as possible and have a very low moisture content. For the making of sweet wafer products a wafer dough having a relatively high sugar content may be used. The wafer products made from such wafer doughs are deformable when they are still warm after the baking operation. That property is utilized in the making of hollow rods. sweet wafer cones for ice cream, sweet wafer rolls, and the like, in a process in which discrete wafer sheets or flat wafer cakes or an endless wafer strip are or is baked first and are or is deformed to the final shape when still soft after the baking operation.

Other wafer products, such as cast wafer cones, wafer cups, wafer discs, low hollow wafers and the like, are baked in their final shape.

Further wafer products are made in that a plurality of wafer sheets are baked and subsequently cooled, coated with cream and stacked to form a wafer block, and the cream-filled wafer block is then cut into discrete small, handy pieces of equal size. Said pieces are packaged individually or in sets and may be airtightly packaged before they are offered for sale.

In dependence on the nature of the products, the wafer products of various kinds may be provided with various coatings, e.g., of sugar or chocolate, and may be filled with various substances, such as ice cream, various other creams, chocolates.

The wafer products described hereinbefore must be distinguished from waffles, which are usually made by housewifes in waffle irons and constitute a soft baked product having a consistency which is similar to that of a roll or pancake. As regards consistency and use, such waffles baked by housewives do not resemble at all the above-described wafer products of the wafer industry.

In the production of wound hollow wafers it is known to provide a winding mold, which receives the substantially flat wafer sheets of wafer cakes emerging from an automatic baking oven, and to wind the wafer sheets or wafer cakes in said winding mold around a winding core to a final shape, such as a cone.

In the production of fan-shaped wafers it is known to bake substantially flat wafer cakes from a sugar-containing wafer dough so that the wafer cakes are deformable in a warm state owing to their high sugar content. Such wafer cakes are folded twice in a warm state so that the originally circular wafer cake is transformed into a fan-shaped wafer having the configuration of a quarter of a circle. That fan-shaped wafer is permitted to cool so that the folded fan shaped wafer is no longer deformable and solidifies to form a baked piece which is crisp and brittle.

Summary of the Invention

It is an object of the invention to provide for the production of baked pieces which comprise two or more wafer layers from discrete flat wafer cakes, which have been baked from sugar-containing wafer dough, a novel process which permits the production of entirely novel baked pieces.

To accomplish that object at least one edible filling material is introduced into said at least one cavity as said wafer cake is folded, a food-grade insulating substance for insulating the flat wafer cake against an ingress of moisture is optionally applied to at least one side of the wafer cake before the latter is folded, and the laminated baked piece is optionally trimmed at an edge thereof which is formed by an edge of the wafer cake.

The process in accordance with the invention can be used to make baked pieces which comprise two wafer layers and between said two wafer layers contain a thin layer of a different substance, such as chocolate, or to make baked pieces comprising two wafer layers, which define a cavity that is filled, e.g., with cream, or to make baked pieces which comprise three of four wafer layers and different substances between said wafer layers. The resulting baked piece may have virtually any desired external shape, which may be determined by the selection of the configuration of the initial contour of the wafer cake and by the manner in which the wafer cake is folded. For instance, a substantially circular wafer cake may be folded along a diameter of the circle to form a substantially semicircular baked piece comprising two wafer layers, and said baked piece may be folded along a radius of the circle to form a baked piece which comprises four wafer layers and has the configuration of a 90° sector of a circle.

Alternatively, a wafer cake having the configuration of a sector of a circle may be folded along two radio of the circle to form a baked piece which has the shape of a sector of a circle and comprises three wafer layers.

Within the scope of the invention the resulting baked piece may be trimmed along an edge which consists of an edge of the flat wafer cake so that it is possible to use wafer cakes which do not have an exactly predetermined edge configuration.

Within the scope of the invention, an insulating

substance for preventing an ingress of moisture may be applied to the still unfolded wafer cake on that surface thereof which is on the outside during the folding operation. The resulting baked piece will remain crisp for a very long time. Alternatively, the insulating substance for preventing an ingress of moisture may be applied to the wafer cake on that side thereof which is disposed on the inside during the folding operation. This will be particularly desirable if a filling material which releases liquid, such as marmelade, is introduced during the folding operation into the cavity which is formed by the folding operation. The filling material may be an edible substance which may contain one or more taste-imparting components and may consist, e.g., of hazelnut cream.

In an embodiment of the process in accordance with the invention at least one edible filling material is introduced during the folding of the wafer cake into the cavity which is formed by the wafer cake as it is folded, and said cavity is subsequently closed in that the edges of the wafer cake are forced against each other. That embodiment may be carried out to form a baked piece which comprises of two wafer layers and is filled, e.g., with cream.

In another embodiment of the process in accordance with the invention, the flat wafer cake, which has optionally been insulated against an ingress of moisture, is folded to form a filled baked piece comprising two wafer layers and is subsequently folded at least once. That embodiment of the process results in a baked piece comprising four crisp wafer layers.

A baked piece which is particularly crisp can be obtained within the scope of the invention in that the flat wafer cake is first folded once to form a baked piece comprising two wafer layers, at least one food-grade insulating substance for preventing an ingress of moisture is applied to at least one side of said baked piece comprising two wafer layers, said baked piece is subsequently folded to define a cavity, and at least one edible filling material is introduced into said cavity during the folding of said baked piece, whereby a laminated baked piece is formed, which may optionally be trimmed at that edge which consists of an edge of the flat wafer cake.

In this manner it is possible to provide a baked piece which comprises four, six or eight wafer layers and two adjacent cream layers, which are separated by two wafer layers if a cream has been applied to the flat wafer cake or to the cavity which is defined as the wafer cake or a baked piece formed as an intermediate product is folded.

Within the scope of the invention the filling materials may be introduced between adjacent wafer layers in that at least one edible substance which contains one or more taste-imparting components is applied to the still unfolded flat wafer cake on that side thereof which is disposed on the inside during the folding operation.

Also within the scope of the invention the still unfolded flat wafer cake may be insulated on one side or both sides against an ingress of moisture before a filling material is applied or introduced. The insulating substance may consist of peanut butter or coconut butter, which is applied as a highly fluid liquid to form an insulating film on the surface of the flat wafer cake.

Brief Description of the Drawing

Figure 1 is a top plan view showing a circular flat wafer cake cream.

Figure 2 is a sectional view showing a baked piece made from the flat wafer cake of Figure 1.

Figure 3 shows a baked piece which has the configuration of a sector of a circle and comprises four wafer layers.

Figure 4 shows a flat wafer cake which has the configuration of a sector of a circle.

Figure 5 shows the baked piece made from the flat wafer cake of Figure 4.

Figure 6 is an enlarged longitudinal sectional view showing the baked piece of Figure 5.

Detailed Description of the Preferred Embodiments

Some wafer products made by the process in accordance with the invention and flat wafer cakes for use therein are diagrammatically shown on the drawings.

To obtain the baked piece of Figure 2, the flat wafer cake shown in Figure 1 is folded about a diametral fold line and filled with cream as it is folded.

The baked piece shown in Figure 3 is obtained in that the baked piece of Figure 2 is folded about a radial fold line and filled with cream as it is folded.

The baked piece of Figure 5 is formed in that the flat wafer cake of Figure 4 is folded about two intersecting fold lines. During the folding operation, a cavity is formed, which is defined by the superimposed portion of the flat wafer cake. Those edge portions of the wafer cake which constitute the unfolded edge of the fanshaped baked piece are forced together to close that cavity and are trimmed to give the baked piece at that edge the desired configuration so that the fan-shaped wafer has exactly defined edge portions and the filling material that has been introduced into the cavity during the folding operation is enclosed by the folded wafer cake on all sides.

Before the flat wafer cake is folded, an insulating substance for preventing an ingress of moisture is applied to the flat wafer cake on that side which is intended to face inwardly during the folding operation. As a result, the baked piece comprising three wafer layers may be filled during the folding operation with a filling material which releases moisture.

CLAIMS

1. A process of making a baked piece from a substantially flat, discrete wafer cake baked from wafer dough, wherein said wafer cake is folded at least once in a soft and deformable state to form a laminated baked piece comprising at least two wafer layers, which define at least one cavity, characterized in that at least one edible filling material is introduced into said at least one cavity as said wafer cake is folded, a food-grade insulating substance for insulating the flat wafer cake against an ingress of moisture is optionally applied to at least one side of the wafer cake before the latter is folded, and the laminated baked piece is optionally trimmed at an edge thereof which is formed by an edge of the wafer cake.

2. A process according to claim 1, characterized in that the cavity which is formed as the wafer cake is folded is closed in that those edges of the baked piece

which consist of edges of the wafer cake are forced against each other after the filling material has been introduced.

3. A process according to claim 1, characterized in that the filled baked piece which comprises two wafer layers and has been formed by the folding of the wafer cake, which has optionally been insulated against an ingress of moisture, is additionally folded at least once.

4. A process according to claim 1, characterized in that the flat wafer cake is first folded once to form a baked piece comprising two wafer layers, at least one food-grade insulating substance for preventing an ingress of moisture is applied to at least one side of said baked piece comprising two wafer layers, said baked piece is subsequently folded to define a cavity, and at least one edible filling material is introduced into said cavity during the folding of said baked piece, whereby a laminated baked piece is formed, which may optionally be trimmed at that edge which consists of an edge of the flat wafer cake.

5. A process of making a baked piece from a substantially flat, discrete wafer cake baked from wafer dough, wherein said wafer cake is folded at least once in a soft and deformable state to form a laminated baked piece comprising at least two wafer layers, which define at least one cavity, substantially as described hereinbefore.

6. A process of making a baked piece from a substantially flat, discrete wafer cake baked from wafer dough, substantially as described hereinbefore.

7. A baked piece comprising at least two wafer layers defining at least one cavity and at least one filling material in said at least one cavity, whenever made by a process according to any of claims 1 to 6.

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